

Film Capacitors

EMI Suppression Capacitors (MKP)

 Series/Type:
 B32924*4 ... B32928*4

 Date:
 June 2018

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EMI suppression capacitors (MKP)

X2 / 350 V AC

B32924*4 ... B32928*4

Typical applications

- X2 class for interference suppression
- Severe ambient conditions
- "E-meters", "In-series" with mains
- "Across the line" applications

Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1:2013): 40/110/56

Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Internal series construction
- Good self-healing properties
- High current handling
- RoHS-compatible
- Stable capacitance in severe ambient conditions 85 °C, 85% RH, 330 V AC, 1000 h
- AEC-Q200D compliant

Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

Marking

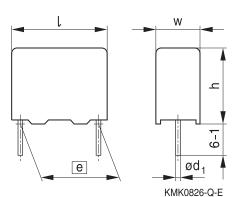
Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage (IEC), series number, sub-class (X2), dielectric code (MKP), climatic category, passive flammability category, approvals

Delivery mode

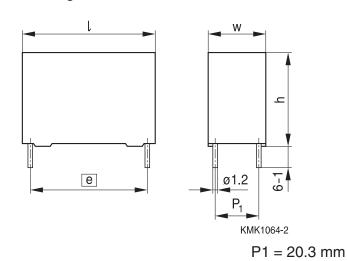
Bulk (untaped) Taped (Ammo pack or reel) For taping details, refer to chapter "Taping and packing".

Dimensional drawing

Drawing 1







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Dimensions in mm

Pins	Lead spacing @ ±0.4	Lead diameter d ₁ ±0.05	Туре	Drawing
2	27.5	0.8	B32924*4	1
2	37.5	1.0	B32926*4	1
4	37.5	1.2	B32926*4	2
4	52.5	1.2	B32928*4	2



B32924*4 ... B32928*4 X2 / 350 V AC



Marking example (position of marks may vary):



Approvals

Approval marks	Standards	Certificate
15	UL 60384-14.2014 CSA E60384-14:2013	ENEC-01393 (approved by UL)
c Al us	UL 60384-14.2014 CSA E60384-14:2013	E97863 (approved by UL)

Overview of available types

Lead spacing	27.5 mm	37.5 mm	52.5 mm
Туре	B32924*4	B32926*4	B32928*4
C _R (μF)			
0.47			
0.56			
0.68			
0.82			
1.0			
1.2			
1.5			
1.8			
2.2			
2.7			
3.3			
4.7			
5.6			
6.8			
8.2			
10			
15			
20			



X2

B32924*4

X2 / 350 V AC

Ordering codes and packing units (lead spacing 27.5 mm)

C _R	Max. dimensions	Ordering code	Reel	Untaped	Pins
	$w \times h \times l$	(composition see below)			
μF	mm		pcs./MOQ	pcs./MOQ	
0.47	$11.0 \times 19.0 \times 31.5$	B32924A4474+***	1400	1280	2
0.56	11.0 imes 19.0 imes 31.5	B32924A4564+***	1400	1280	2
0.68	$11.0 \times 21.0 \times 31.5$	B32924A4684+***	1400	1280	2
0.82	$12.5 \times 21.5 \times 31.5$	B32924A4824M***	1200	1120	2
0.82	$13.5\times23.0\times31.5$	B32924B4824K***	1000	1040	2
1.0	$13.5 \times 23.0 \times 31.5$	B32924A4105M***	1000	1040	2
1.0	$14.0 \times 24.5 \times 31.5$	B32924B4105K***	-	1040	2
1.2	$14.0\times24.5\times31.5$	B32924A4125M***	—	1040	2
1.5	$16.0\times32.0\times31.5$	B32924B4155+***	—	880	2
1.5	$18.0\times27.5\times31.5$	B32924A4155+***	—	800	2
1.8	$16.0\times32.0\times31.5$	B32924B4185+***	—	880	2
1.8	$18.0\times27.5\times31.5$	B32924A4185M***	—	800	2
2.2	$18.0\times33.0\times31.5$	B32924S4225+***	—	800	2
2.2	$19.0\times30.0\times31.5$	B32924A4225M***	—	720	2
2.2	$21.0 \times 31.0 \times 31.5$	B32924B4225K***	-	720	2
2.7	$22.0\times33.0\times31.5$	B32924A4275+***	-	640	2
3.3	$22.0\times36.5\times31.5$	B32924A4335M***	-	640	2
3.3	$22.0\times48.0\times31.5$	B32924B4335K***	_	320	2

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - $M = \pm 20\%$
 - K = ±10%

- *** = Packaging code:
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)
 - 003 = Straight terminals, untaped (lead length 3.2 ±0.3 mm)
 - 189 = Straight terminals, Reel



X2 / 350 V AC

B32926*4



Ordering codes and packing units (lead spacing 37.5 mm)

C _R	Max. dimensions	Ordering code	Reel	Untaped	Pins
	$w \times h \times l$	(composition see below)			
μF	mm		pcs./MOQ	pcs./MOQ	
1.0	12.0 × 22.0 × 42.0	B32926A4105+***	_	1620	2
1.2	12.0 imes 22.0 imes 42.0	B32926A4125M***	-	1620	2
1.2	14.0 imes25.0 imes42.0	B32926B4125K***	-	1380	2
1.5	14.0 imes 25.0 imes 42.0	B32926A4155+***	-	1380	2
1.8	$14.0\times25.0\times42.0$	B32926A4185M***	—	1380	2
1.8	16.0 imes 28.5 imes 42.0	B32926B4185K***	-	800	2
2.2	16.0 imes 28.5 imes 42.0	B32926A4225+***	-	800	2
2.7	$17.5\times32.0\times42.0$	B32926A4275M***	—	760	2
2.7	18.0 imes 32.5 imes 42.0	B32926B4275K***	-	720	2
3.3	18.0 imes 32.5 imes 42.0	B32926A4335M***	—	720	2
3.3	$20.0\times 39.5\times 42.0$	B32926B4335K***	—	640	2
4.7	$20.0\times 39.5\times 42.0$	B32926B4475M***	-	640	2
4.7	$28.0\times37.0\times42.0$	B32926A4475K***	—	440	2
5.6	$28.0\times37.0\times42.0$	B32926A4565M***	—	440	2
5.6	$28.0\times42.5\times42.0$	B32926B4565K***	-	440	2
6.8	$28.0\times42.5\times42.0$	B32926A4685+***	-	440	2
8.2	30.0 imes 45.0 imes 42.0	B32926A4825M***	-	400	2
8.2	33.0 imes 48.0 imes 42.0	B32926B4825K***	-	180	4
10.0	$33.0\times48.0\times42.0$	B32926A4106M***	—	180	4

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $M = \pm 20\%$

 $K = \pm 10\%$

- *** = Packaging code:
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)
 - $\begin{array}{rl} \text{003} = & \text{Straight terminals, untaped} \\ & (\text{lead length 3.2 } \pm 0.3 \text{ mm}) \end{array}$
 - 189 = Straight terminals, Reel





B32928*4 X2 / 350 V AC

Ordering codes and packing units (lead spacing 52.5 mm)

C _R	Max. dimensions $w \times h \times I$	Ordering code (composition see below)	Reel	Untaped	Pins
μF	mm		pcs./MOQ	pcs./MOQ	
8.2	$30.0 \times 45.0 \times 57.5$	B32928A4825K***	_	280	4
10.0	$30.0 \times 45.0 \times 57.5$	B32928A4106K***	-	280	4
15.0	35.0 imes 50.0 imes 57.5	B32928A4156K***	_	108	4
20.01)	$45.0\times57.0\times57.5$	B32928A4206K***	_	140	4

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - $M = \pm 20\%$
 - $K = \pm 10\%$

*** = Packaging code:

- 000 = Straight terminals, untaped (lead length 6 -1 mm) 003 = Straight terminals, untaped
- $(lead length 3.2 \pm 0.3 mm)$
- 189 = Straight terminals, Reel

1) Note: No approval marks



X2/350 V AC



Technical data

Reference standard: IEC 60384-14:2013 / UL 60384-14:2014.

All data given at T = 20 °C, unless otherwise specified.

Rated AC voltage	350 V (50/60 Hz)
(IEC 60384-14:2013)	
Maximum continuous DC voltage V_{DC}	650 V DC
Max. operating temperature T _{op,max}	+110 °C
DC test voltage	4.3 · 350 = 1505 V DC, 2 s

The repetition of this DC voltage test may damage the capacitor. Special care must be taken in case of use several capacitors in a parallel configuration.

Dissipation factor tan δ (in 10 ⁻³)		$C_R \le 4.7 \ \mu F$	C _R > 4.7 μF
at 20 $^{\circ}$ C (upper limit values)	at 1 kHz	0.9	1.2
Insulation resistance R_{ins} or time constant $\tau = C_R \cdot R_{ins}$ at 100 V DC, 20 °C, rel. humidity \leq 65% and for 60 s (minimum as-delivered values)	30 000 s		
Passive flammability category	В		
Capacitance tolerances (measured at 1 kHz)	±10% (K), ±20% (M)		
Damp heat test	Test conditions		
	Relative humidity:85% ±2%Voltage value:330 V A0		+85 °C ±2 °C 85% ±2% 330 V AC, 50 Hz 1000 hours
Limit values after damp heat test			





Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

" k_0 " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V²/µs.

Note:

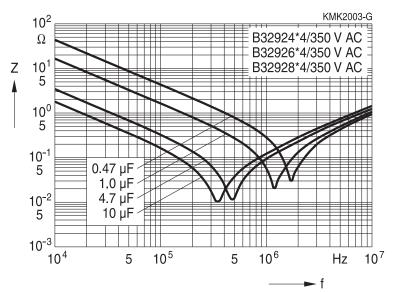
The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt and k₀ values

Lead spacing	27.5 mm	37.5 mm	52.5 mm
dV/dt in V/µs	80	40	30
k₀in V²/μs	27 400	10 400	8 600

Impedance Z versus frequency f

(typical values)

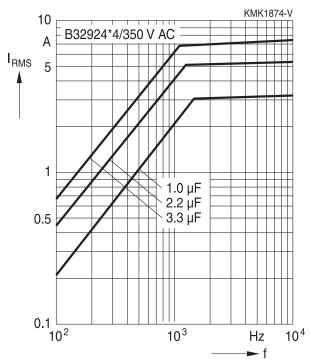




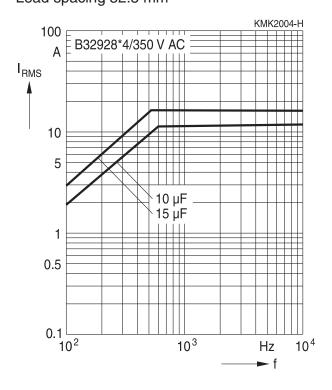


Permissible AC current I_{RMS} versus frequency f (for sinusoidal waveform, TA ${\leq}90$ °C and ${\Delta}ESR$ <100% from receipt condition)

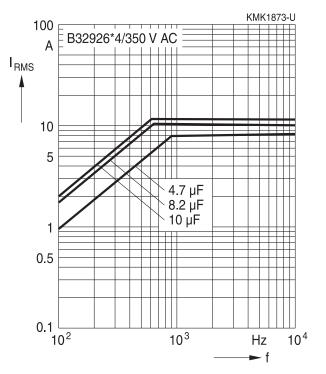
Lead spacing 27.5 mm



Lead spacing 52.5 mm



Lead spacing 37.5 mm







X2 / 350 V AC

Testing and Standards

Test	Reference	Conditions of test		Performance requirements
Voltage proof	IEC 60384-14:2013	Voltage proof between terminals, 4.3 V_R , 2 s Terminals and enclosure: 2 V_R + 1500 V AC Insulation resistance, R_{ins} Capacitance, C Dissipation factor, tan δ		Within specified limits
Robust ness of termina- tions	IEC 60068-2-21:2006	Tensile strength (tes Wire diameter $0.5 < d_1 \le 0.8 \text{ mm}$ $0.8 < d_1 \le 1.25 \text{ mm}$	t Ua1) Tensile force 10 N 20 N	Capacitance and tan δ within specified limits
Resistance to solder- ing heat	IEC 60068-2-20:2008, test Tb, method 1A	Solder bath tempera 260 ±5 °C, immersio 10 seconds		$\Delta C/C_0 \le 5\%$ tan δ within specified limits
Vibration	IEC 60384-14:2013	Test Fc: vibration sinusoidal Displacement: 0.75 mm Accleration: 98 m/s ² Frequency: 10 Hz 500 Hz Test duration: 3 orthogonal axes, 2 hours each axe		No visible damage
Bump	IEC 60384-14:2013	Test Eb: Total 4000 bumps with 400 m/s ² mounted on PCB 6 ms duration		No visible damage $ \Delta C/C_0 \le 5\%$ tan δ within specified limits
Damp heat, steady state	IEC 60384-14:2013	Test Ca 40 °C / 93% RH / 56 days		No visible damage $\begin{split} \Delta C/C_0 &\leq 5\% \\ \Delta \ tan \ \delta &\leq 0.008 \ for \ C &\leq 1 \ \mu F \\ \Delta \ tan \ \delta &\leq 0.005 \ for \ C &> 1 \ \mu F \\ Voltage \ proof \\ R_{ins} &\geq 50\% \ of \ initial \ limit \end{split}$
Special biased damp heat test	_	85 °C / 85% RH / 1000 h / 330 V AC, 50 Hz		$\begin{split} \Delta C/C_0 &\leq 7.5\% \\ \Delta \tan \delta &\leq 0.003 \\ R_{\text{ins}} &\geq 50\% \text{ of initial limit} \end{split}$
Rapid change of tempera- ture	IEC 60384-14:2013	T_A = lower category T_B = upper category 5 cycles, duration t =	temperature	No visible damage $ \Delta C/C_0 \le 5\%$ tan δ within specified limits





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Test	Reference	Conditions of test	Performance requirements
Climatic	IEC	Dry heat Tb / 16 h	No visible damage
sequence	60384-14:2013	Damp heat cyclic, 1 st cycle	$ \Delta C/C_0 \le 5\%$
		+55 °C / 24 h / 95% 100% RH	$ \Delta \tan \delta \le 0.008$ for C $\le 1 \ \mu F$
		Cold Ta / 2 h	$ \Delta \tan \delta \le 0.005$ for C > 1 μ F
		Damp heat cyclic, 5 cycles	Voltage proof
		+55 °C / 24 h / 95% 100% RH	$R_{ins} \ge 50\%$ of initial limit
Impulse	IEC	3 impulses	No visible damage
test	60384-14:2013	Tb / 1.25 V_{R} / 1000 hours,	$ \Delta C/C_0 \le 10\%$
Endurance		1000 V_{RMS} for 0.1 s every hour	$ \Delta \tan \delta \le 0.008$ for C $\le 1 \ \mu F$
			$ \Delta \tan \delta \le 0.005$ for C > 1 μ F
			Voltage proof
			$R_{ins} \ge 50\%$ of initial limit
Passive	IEC	Flame applied for a period of time	В
flamma-	60384-14:2013	depending on capacitor volume	
bility			
Active	IEC	20 discharges at 2.5 kV + V_R	The cheesecloth shall not
flamma-	60384-14:2013		burn with a flame
bility			

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 + 0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder





1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1. Conditions:

Series	8	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP			
MKP	(lead spacing >7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5±1 s
MKP MKT	(lead spacing ≤7.5 mm) uncoated (lead spacing ≤10 mm) insulated (B32559)		<4 s recommended soldering profile for MKT uncoated (lead spacing \leq 10 mm) and insulated (B32559)
300	КМК1242-V	,	
°C 250 200 150 100 50 0	260°C, 4 s	50	
<u> </u>	> t		
Immersion depth		2.0 + 0/-0.5 mm from capacitor body or seating plane	
Shield		Heat-absorbing board, (1.5 ± 0.5) mm thick, between capacitor body and liquid solder	
Evaluation criteria:			
Visua	l inspection	No visible damage	
$\Delta C/C_0$	-	2% for MKT/MKP/MFP 5% for EMI suppression of	capacitors
$tan \delta$		As specified in sectional specification	

Please read *Cautions and warnings* and *Important notes* at the end of this document.

Page 12 of 22



X2 / 350 V AC

X2

1.3 General notes on soldering

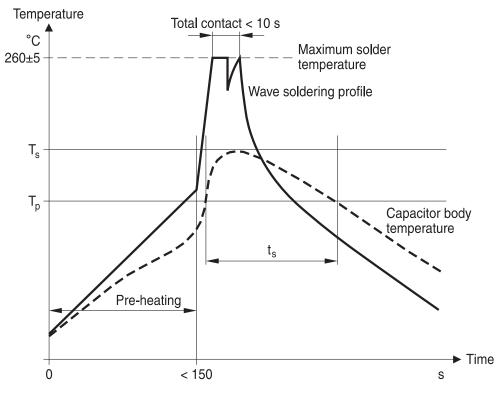
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
- diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



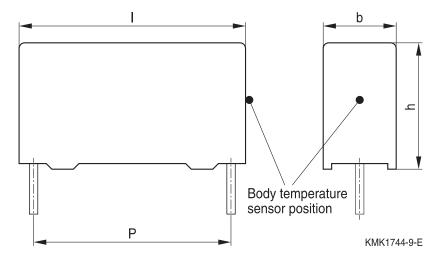
 $T_{s}: Capacitor body maximum temperature at wave soldering \\T_{p}: Capacitor body maximum temperature at pre-heating \\KMK1745-A-E$

Please read *Cautions and warnings* and *Important notes* at the end of this document.

Page 13 of 22







Body temperature should follow the description below:

- MKP capacitor During pre-heating: T_p ≤110 °C During soldering: T_s ≤120 °C, t_s ≤45 s
- MKT capacitor During pre-heating: T_p ≤125 °C During soldering: T_s ≤160 °C, t_s ≤45 s

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be \leq 120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be <360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings \leq 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Please refer to EPCOS Film Capacitor Data Book in case more details are needed.



X2 / 350 V AC



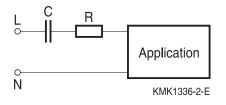
Application note for the different possible X1 / X2 positions

In series with the powerline (i.e. capacitive power supply)

Typical Applications:

- Power meters
- ECUs for white goods and household appliances
- Different sensor applications
- Severe ambient conditions

Basic circuit



Required features

- High capacitance stability over the lifetime
- Narrow tolerances for a controlled current supply

Recommended EPCOS product series

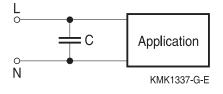
- B3293* (305 V AC) heavy duty with EN approval for X2 (UL Q1/2010)
- B3265* MKP series standard MKP capacitor without safety approvals
- B3267*L MKP series standard MKP capacitor without safety approvals
- B3292*H/J (305 V AC), severe ambient condition, approved as X2

In parallel with the powerline

Typical Applications:

Standard X2 are used parallel over the mains for reducing electromagnetic interferences coming from the grid. For such purposes they must meet the applicable EMC directives and standards.

Basic circuit



Required features

- Standard safety approvals (ENEC, UL, CSA, CQC)
- High pulse load capability
- Withstand surge voltages

Recommended EPCOS product series

- B3292*C/D (305 V AC) standard series, approved as X2
- B3291* (330 V AC), approved as X1
- B3291* (530 V AC), approved as X1
- B3292*H/J (305 V AC), severe ambient condition, approved as X2





X2 / 350 V AC

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of EPCOS.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Торіс	Safety information	Reference chapter
		"General technical
		information"
Storage	Make sure that capacitors are stored within the specified	4.5
conditions	range of time, temperature and humidity conditions.	"Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive	5.3
	flammability), avoid overload of the capacitors (active	"Flammability"
	flammability) and consider the flammability of materials.	
Resistance to	Do not exceed the tested ability to withstand vibration.	5.2
vibration	The capacitors are tested to IEC 60068-2-6:2007.	"Resistance to
	EPCOS offers film capacitors specially designed for	vibration"
	operation under more severe vibration regimes such as	
	those found in automotive applications. Consult our	
	catalog "Film Capacitors for Automotive Electronics".	

Торіс	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits	1 "Soldering"
	during soldering.	
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"



X2 / 350 V AC



Торіс	Safety information	Reference chapter
		"Mounting guidelines"
Embedding of	When embedding finished circuit assemblies in plastic	3 "Embedding of
capacitors in	resins, chemical and thermal influences must be taken	capacitors in finished
finished	into account.	assemblies"
assemblies	Caution: Consult us first, if you also wish to embed other	
	uncoated component types!	

Design of EMI Capacitors

EPCOS EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC 60384-14:2013 (4th edition) / UL 60384-14:2014 (2nd edition) must be performed at 1.25 × V_R at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC 60384-14:2013 (4th edition) / UL 60384-14:2014 (2nd edition) establishes high voltage tests performed at 4.3 × V_R −1 minute, impulse testing at 2500 V for C = 1 µF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.

Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products**. Detailed information can be found on the Internet under <u>www.epcos.com/orderingcodes</u>.





X2/350 V AC

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{c}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
βc	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C _R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation	
	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
$\Delta tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung
	of voltage rise)	(Spannungsflankensteilheit)
$\Delta V / \Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen
		Wechselspannung
f ₂	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte
	AC voltage due to current limit	Reduzierung der zulässigen
		Wechselspannung
f _r	Resonant frequency	Resonanzfrequenz
F _D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F _τ	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _c	Category current (max. continuous	Kategoriestrom (max. Dauerstrom)
	current)	





X2 / 350 V AC

Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i _z	Capacitance drift	Inkonstanz der Kapazität
k _o	Pulse characteristic	Impulskennwert
L _s	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λο	Constant failure rate during useful	Konstante Ausfallrate in der
Ũ	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P _{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R _i	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R _P	Parallel resistance	Parallelwiderstand
Rs	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{oL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T _{op}	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T _R	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer





X2 / 350 V AC

Symbol	English	German
V _{AC}	AC voltage	Wechselspannung
V _c	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V _i	Input voltage	Eingangsspannung
Vo	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V _p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V _R	Rated voltage	Nennspannung
ν _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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